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APPLICANT : JSR CORP;

INVENTOR : KURIHARA FUMIO;

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TITLE : POLYMERIDE COMPOSITION FOR POLISHING PAD, AND POLISHING PAD USING IT

ABSTRACT : PROBLEM TO BE SOLVED: To provide a polymeride composition for a polishing pad and a polishing pad capable of serving well for polishing a semiconductor wafer, etc.

SOLUTION: A polymeride composition consists of a knead containing 57 parts by wt. thermoplastic polyester elastomer as a thermoplastic polymeride which is non-soluble to the water and 43 parts by wt. β -cyclodextrin as a water soluble substance (including a substance having water absorptiveness). This composition for a polishing pad has a volume swelling rate of 20% or less in case dipped in a 23-°C water for three days and exhibits a drop of Shore D hardness of 10 or less in case dipped in a 23-°C water for three days. Because of containing much β -cyclodextrin, the composition has a large intrusion hardness, and a polishing pad excellent in the polishing speed can be obtained.

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